

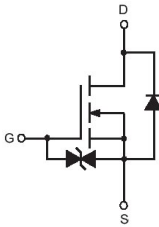
/ Descriptions

/ Features

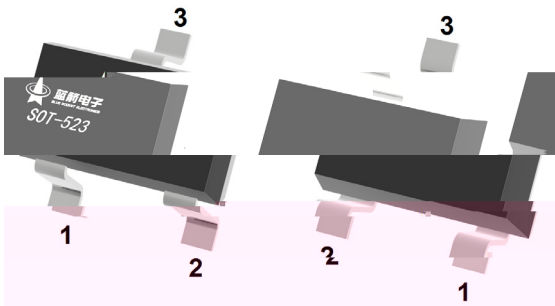
2KV

/ Applications

/ Equivalent Circuit



/ Pinning



/ Marking

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/ Electrical Characteristic Curve

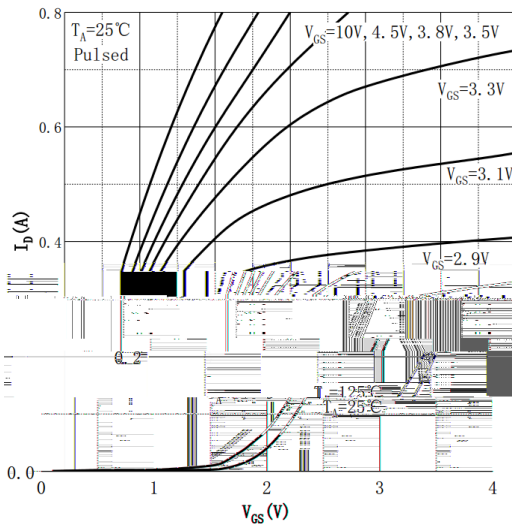


Figure.2 Transfer Characteristics

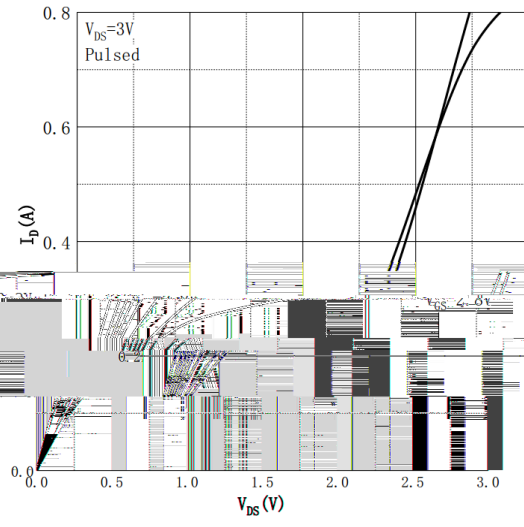


Figure.1 Output Characteristics

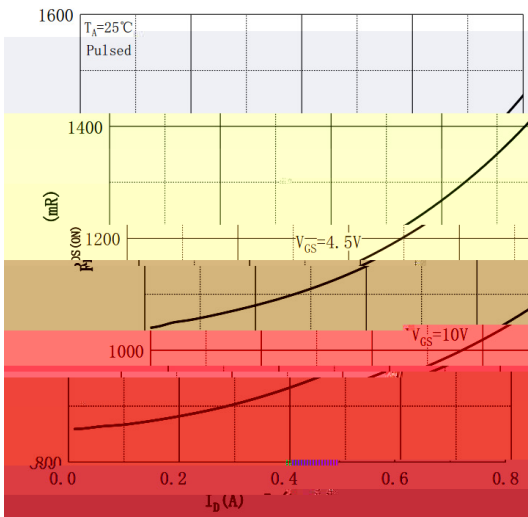


Figure.3 On-Resistance vs Drain Current

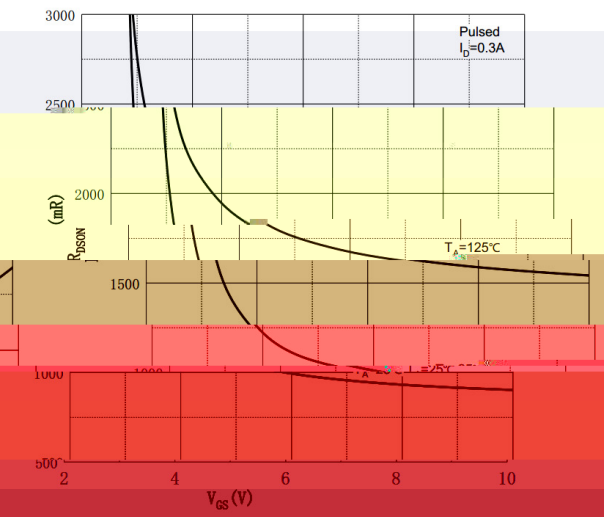


Figure.4 Thermal Resistance vs Gate-Source Voltage

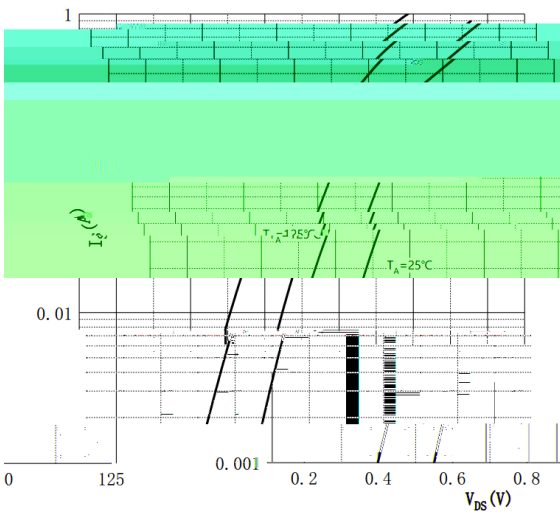


Figure.5 Diode Forward Voltage vs Current

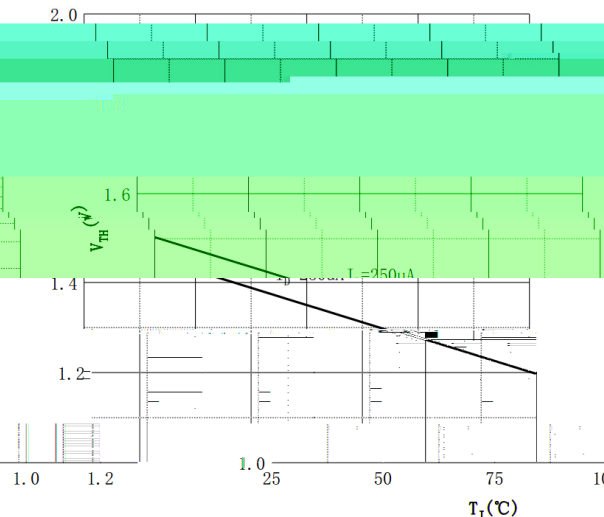
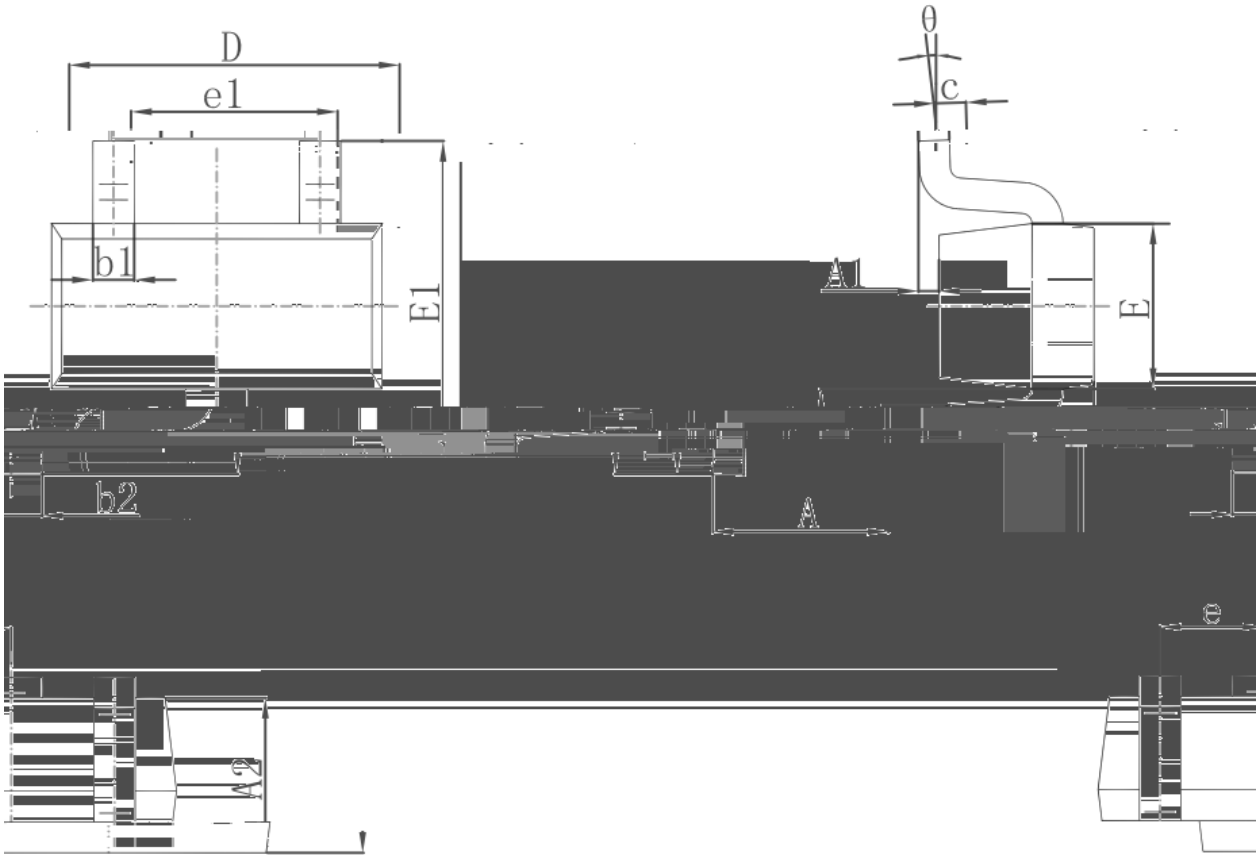


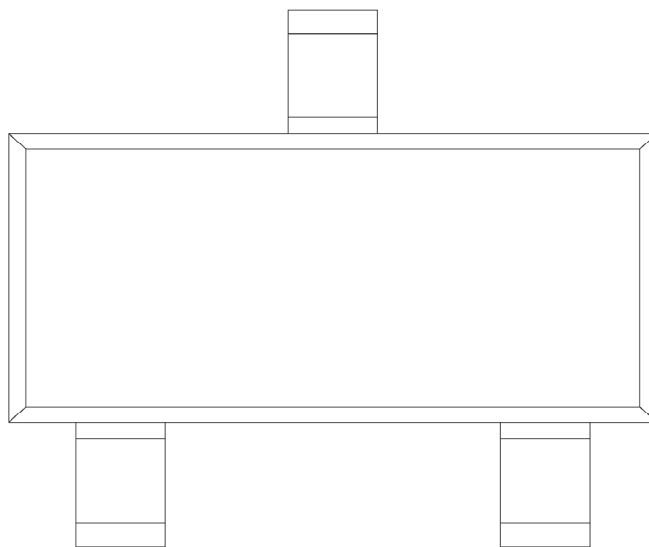
Figure.6 Threshold Voltage vs Temperature

/ Package Dimensions

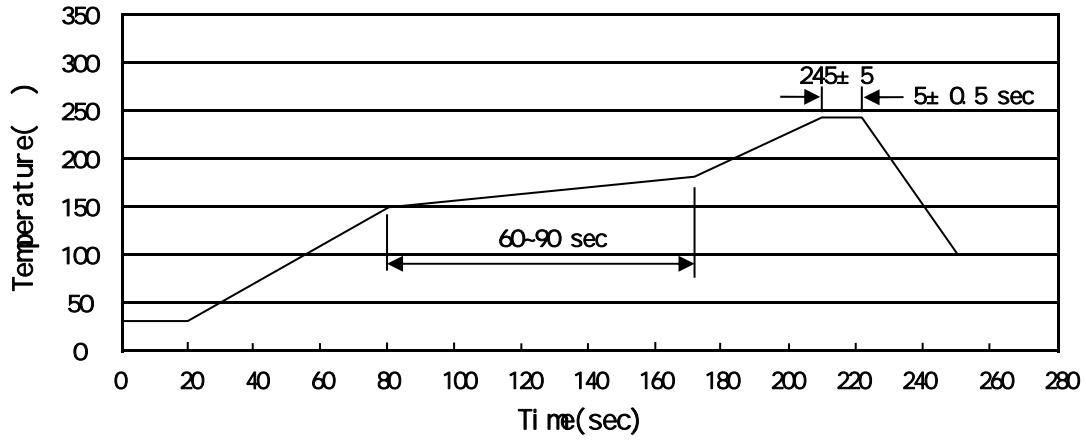


Symbol	Dimensions In Millimeters		Dimensions In Inches		Symbol
	Min.	Max.	Min.	Max.	
A	0.700	0.900	0.028	0.035	A
e1	0.900	1.100	0.035	0.043	e1
e	0.700	0.800	0.028	0.031	e
b2	0.250	0.350	0.010	0.014	b2
L	0.200	0.050	0.008	0.002	L
theta	1.700	0.059	0.067	0.002	theta
c	0.900	0.028	0.035	0.001	c
E1	1.450	1.750	0.057	0.069	E1
e	0.500 TYP.		0.020 TYP.		e
e1	0.900	1.100	0.035	0.043	e1
L	0.400 REF.		0.016 REF.		L
theta	0.260	0.460	0.010	0.018	theta
c	0	0	0	0	c

/ Marking Instructions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.


/ Notices